

# Vincent Bley

## List of Publications by Year in descending order

Source: <https://exaly.com/author-pdf/11709159/publications.pdf>

Version: 2024-02-01

12  
papers

230  
citations

1163117

8  
h-index

1281871

11  
g-index

12  
all docs

12  
docs citations

12  
times ranked

266  
citing authors

| #  | ARTICLE  | IF  | CITATIONS |
|----|--|-----|-----------|
| 1  | Hydrothermal synthesis of nanosized BaTiO powders and dielectric properties of corresponding ceramics. Solid State Ionics, 2005, 176, 1301-1309.   | 2.7 | 91        |
| 2  | Contribution to the understanding of the relationship between mechanical and dielectric strengths of Alumina. Journal of the European Ceramic Society, 2010, 30, 3117-3123.                        | 5.7 | 47        |
| 3  | Direct Copper Bonding for Power Interconnects: Design, Manufacturing, and Test. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2015, 5, 143-150.                         | 2.5 | 17        |
| 4  | Electrical and Physical Characterization of Bulk Ceramics and Thick Layers of Barium Titanate Manufactured Using Nanopowders. Journal of Materials Engineering and Performance, 2007, 16, 626-634. | 2.5 | 16        |
| 5  | Application of the Spark Plasma Sintering Technique to Low-Temperature Copper Bonding. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2012, 2, 553-560.                  | 2.5 | 12        |
| 6  | Impact of a surface laser treatment on the dielectric strength of $\alpha$ -alumina. Journal of Applied Physics, 2009, 106, 094103.  | 2.5 | 11        |
| 7  | A Lab-Scale Alternative Interconnection Solution of Semiconductor Dice Compatible with Power Modules 3-D Integration. IEEE Transactions on Power Electronics, 2010, 25, 1667-1670.                 | 7.9 | 11        |
| 8  | PCB dual-switch fuse with energetic materials embedded: Application for new fail-safe and fault-tolerant converters. Microelectronics Reliability, 2012, 52, 2457-2464.                            | 1.7 | 9         |
| 9  | Soft ferrite cores characterization for integrated micro-inductors. Journal of Micromechanics and Microengineering, 2014, 24, 104003.  | 2.6 | 8         |
| 10 | Soft ferrite cores characterization for integrated micro-inductors. Journal of Physics: Conference Series, 2013, 476, 012139.  | 0.4 | 5         |
| 11 | Low-profile small-size ferrite cores for powerSiP integrated inductors. , 2013, , .  |     | 2         |
| 12 | Fast cut-off, low I <sup>2</sup> T and high temperature monolithic on-chip fuse on silicon substrate for new fail-safe embedded power switch. Microelectronics Reliability, 2021, 126, 114240.     | 1.7 | 1         |